

CLAIMS:

1. An electronic device comprising a body of electrically insulating material that is provided with a through-hole or cavity, in which an electric component is present, the component being attached to the body through an attachment layer, provided with a pattern of electrical conductors for electrically coupling the component to other components and/or
5 contact means for external coupling, at least one of which electrical conductors extends into the body and is electrically coupled to a further conductor that is embedded in the body and is at least partially exposed to a surface of the body.
2. A device as claimed in Claim 1, wherein the body further comprises embedded
10 components, which are coupled electrically to the same pattern of electrical conductors.
3. A device as claimed in Claim 1, wherein the component is chosen from the group of optically active and optically sensitive components.
- 15 4. A device as claimed in Claim 3, wherein the electrically insulating material of the body is an optically transparent material, and there is a light path to the component through the body of transparent material.
5. A device as claimed in Claim 1, wherein the pattern of conductors extends in a
20 first and a second plane, said planes including an angle unequal to 180 °.
6. A device as claimed in Claim 5, wherein the conductors at the first plane include contact means for electrical coupling to an external device and said component is coupled to conductors located at the second plane.
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7. A device as claimed in Claim 6, wherein the component is chosen from the group of optically active and optically sensitive components.

8. A device as claimed in Claim 1, wherein the electrical conductors are mechanically anchored in the body and/or in the attachment layer.
9. A device as claimed in Claim 1, further provided with an integrated shield.
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10. A method of manufacturing an electronic device comprising a body of electrically insulating material provided with a pattern of electrical conductors, said method comprising the steps of:
- 10 – providing a carrier with at a first side the pattern of electrical conductors and at an opposed second side a sacrificial layer;
 - providing an attachment layer at the first side;
 - mounting a first electric component at the first side of the carrier, therewith also providing electrical coupling from the component to contact pads in the pattern of conductors
 - 15 – providing the body of electrically insulating material in a moulding process at the first side of the carrier, such that the first component is kept outside the body, and
 - removing the sacrificial layer of the carrier at least partially.
11. A method as claimed in Claim 10, characterized in that a second electric
- 20 component is mounted at the first side of the carrier before the provision of the body, which second component is thereafter encapsulated in the body.